

**Product Texts**

LNP THERMOCOMP EC005 compound is based on Polyetherimide (PEI) resin containing 25% carbon fiber. Added features of this grade include: Electrically Conductive.

Processing/Physical Characteristics	Value	Unit	Test Standard
<b>ISO Data</b>			
Molding shrinkage, parallel	0.2	%	ISO 294-4, 2577
Molding shrinkage, normal	0.4	%	ISO 294-4, 2577

Mechanical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
Tensile Modulus	18400	MPa	ISO 527
Stress at break	200	MPa	ISO 527
Strain at break	1.3	%	ISO 527
Flexural modulus	13600	MPa	ISO 178
Izod impact strength, +23°C, 4mm	35	kJ/m <sup>2</sup>	ISO 180/1U
Izod notched impact strength, +23°C, 4mm	6	kJ/m <sup>2</sup>	ISO 180/1A

Thermal properties	Value	Unit	Test Standard
<b>ISO Data</b>			
Temp. of deflection under load, 1.80 MPa	214	°C	ISO 75-1/-2

Electrical properties	Value	Unit	Test Standard
<b>ASTM Data</b>			
Surface Resistivity	10000	Ohm	ASTM D 257

Other properties	Value	Unit	Test Standard
Density	1370	kg/m <sup>3</sup>	ISO 1183

Processing Recommendation Injection Molding	Value	Unit	Test Standard
Pre-drying - Temperature	150	°C	-
Pre-drying - Time	4 - 6	h	-
Processing humidity	≤0.02	%	-
Melt temperature	360 - 400	°C	-
Mold temperature	140 - 180	°C	-
Zone 1	360 - 380	°C	-
Zone 2	370 - 390	°C	-
Zone 3	380 - 400	°C	-
Back pressure	0.3 - 0.7	MPa	-

**Characteristics****Processing**

Injection Molding

**Applications**

Automotive

**Special Characteristics**

Increased electrical conductivity

**Regional Availability**

Europe